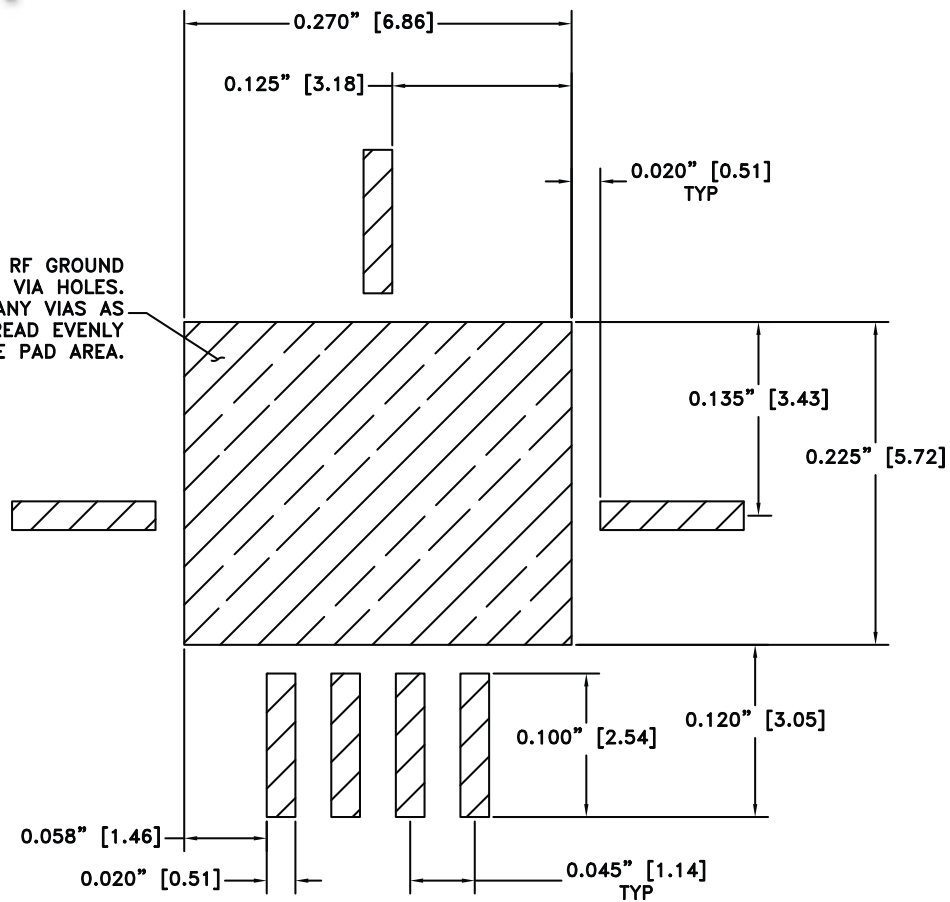


**G7 – 7 LEAD GLASS/METAL
HERMETIC SMT PACKAGE**

Suggested G7 PCB Land Pattern



CONNECT TO RF GROUND
WITH MULTIPLE VIA HOLES.
USE AS MANY VIAS AS
POSSIBLE, SPREAD EVENLY
OVER THE PAD AREA.



NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.